

(0,635 mm) .025"

QFS SERIES

RUGGED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

Insulator Material: Liquid Crystal Polymer Contact & Ground Plane Material: Phosphor Bronze

Plating: Au over 50µ" (1,27 µm) Ni (Tin on Ground Plane Tail) Current Rating: Contact:

2.6 A per pin (1 pin powered per row) Ground Plane: 15.7 A per ground plane (1 ground plane powered) Voltage Rating: 300 VAC mated with QMS Operating Temp: -55°C to ±125°C

RoHS Compliant: Yes Processing:

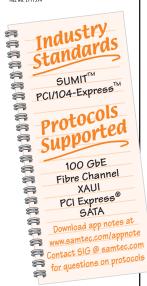
Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (026-078) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





Note: Some lengths, styles and options are non-standard, non-returnable.

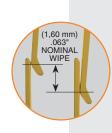


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Cable Mates:

OMS/OES

QFS



Increased insertion depth for rugged applications

Integral metal plane for power or ground

Rated @ 3dB Insertion Loss
PCB effects* w/o PCB effects**

ALSO AVAILABLE (MOQ Required)

- Other platings
- Without PCB Alignment Pins
- Hot Pluggable
- 4 banks (104 -SE, 64 -DP) Contact Samtec.

นเพอ/นาอ	Type	Hatou C oub moortion 2000		
10 mm Stack Height		with PCB effects*	w/o PCB effects**	
Single-Ended Signaling	-D	9 GHz / 18 Gbps	8 GHz / 16 Gbps	
Differential Pair Signaling	-D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps	
Differential Pair Signaling	-DP	7.5 GHz / 15 Gbps	9 GHz / 18 Gbps	
		44 . 4		

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

PINS PER ROW

NO. OF PAIRS

MATED HEIGHT*

-05.75

10 mm

12 mm

GP = No. of Banks x (21,34) .840 + (12,45) .490

No. of Banks x (21,34) .840 + (1,02) .040 →

*Processing conditions will affect mated height.

QMS LEAD STYLE

-06.75

11 mm

13 mm

-026, -052, -078 (52 total pins per bank = -D)

-016, -032, -048 (16 pairs per bank = -D-DP)

Α

(7,44) .293

-(21,34) .840

-D

-06.25 (9,42) .371

LEAD

STYLE

-04.25

(8,13)

.320

(0,89)

Performance data for other stack heights and complete test data available at www.samtec.com?QFS or contact sig@samtec.com

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28 G b p s

PLATING OPTION

ТҮРЕ

OTHER OPTION

— **L** (–04.25 lead style only) = 10u" (0.25 um) Gold on Si

LEAD

STYLE

Specify

LEAD

STYLE

from

chart

-09.75

14 mm

16 mm

(0,635)

= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

-SL

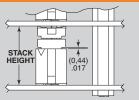
(-06.25 lead style only) = 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)



-D = Single-Ended

-D-DP = Differential Pair (-04.25 lead style only) -GP = Guide Holes (-04.25 lead style only)

APPLICATION



Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY	INTERCONNECTS						
STANDARD	TERMINAL	SOCKET	BANKS	STACK HEIGHT			
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm			
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm			
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm			
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm			
PCI/104-Express	ASP-142/81-03	ASP-129646-03	3	22 mm			

(1,02) .040 DIA → i ←

-D-DP